

Form PTO 1449
(Modified)U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY DOCKET NO.
202321US2SERIAL NO.
New Application

LIST OF REFERENCES CITED BY APPLICANT

APPLICANT

Sugitaka OTEKI, et al.

FILING DATE
Herewith

GROUP

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
<i>WA</i>	AA	5,050,221	09/17/91	Junichi OHTA, et al.			
<i>WA</i>	AB	6,041,139	03/21/00	Hiromi OKUBO, et al.			
<i>WA</i>	AC	6,151,457	11/21/00	Hiroyuki KAWAMOTO			
	AD						
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	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
	AM						
	AN						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES	NO
	AO					
	AP					
	AQ					
	AR					
	AS					
	AT					
	AU					
	AV					

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)

	AW	
	AX	
	AY	
	AZ	

Examiner

Date Considered

*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

 970 U.S. PTO
09/17/02
01/29/01



LIST OF RELATED CASES

<u>Docket Number</u>	<u>Serial or Patent Number</u>	<u>Filing or Issue Date</u>	<u>Inventor/ Applicant</u>
202321US2*	09/770,214	01/29/01	OTEKI et al. <i>N</i>
242914US2	10/663,784	09/17/03	SHIRATA et al. <i>dl</i>

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*Present Application; listed for information

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LIST OF RELATED CASES

<u>Docket Number</u>	<u>Serial or Patent Number</u>	<u>Filing or Issue Date</u>	<u>Inventor/ Applicant</u>
202321US2*	09/770,214	01/29/01	OTEKI et al. <i>NY</i>
243080US2	10/668,360	09/24/03	OHYAMA et al. <i>NY</i>

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<u>Docket Number</u>	<u>Serial or Patent Number</u>	<u>Filing or Issue Date</u>	<u>Inventor/ Applicant</u>
202321US2*	09/770,214	01/29/01	OTEKI et al. <i>NU</i>
245245US2	10/703,509	11/10/03	NOMIZU et al. <i>NU</i>

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